

Title (en)

PRODUCTION METHOD FOR AN ENCAPSULATED MICROMECHANICAL COMPONENT, CORRESPONDING MICROMECHANICAL COMPONENT AND ENCAPSULATION FOR A MICROMECHANICAL COMPONENT

Title (de)

HERSTELLUNGSVERFAHREN FÜR EIN VERKAPPTES MIKROMECHANISCHES BAUELEMENT, ENTSPRECHENDES MIKROMECHANISCHES BAUELEMENT UND KAPPE FÜR EIN MIKROMECHANISCHES BAUELEMENT

Title (fr)

PROCÉDÉ DE RÉALISATION D'UN COMPOSANT MICRO-MÉCANIQUE PROTÉGÉ, COMPOSANT MICRO-MÉCANIQUE CORRESPONDANT ET PROTECTION POUR COMPOSANT MICRO-MÉCANIQUE

Publication

EP 2473438 A1 20120711 (DE)

Application

EP 10739911 A 20100802

Priority

- DE 102009029184 A 20090903
- EP 2010061185 W 20100802

Abstract (en)

[origin: WO2011026699A1] The present invention provides a production method for an encapsulated micromechanical component, a corresponding micromechanical component and an encapsulation for a micromechanical component. The method has the following steps: forming an intermediate substrate (1, 1', 1"; 2, 2') with a plurality of perforations (K; K'); laminating an encapsulation substrate (KD; KD') onto a front side (VS; VS') of the intermediate substrate (1, 1', 1"; 2, 2'), which closes the perforations (K; K') on the front side (VS; VS'), and laminating a functional MEMS wafer (3; 3') onto a rear side (RS; RS') of the intermediate substrate (1, 1', 1"; 2, 2'), the functional MEMS wafer (3; 3') being aligned with the intermediate substrate (1, 1', 1"; 2, 2') in such a way that the perforations (K; K') form respective cavities over corresponding functional regions (FB; FB') of the functional MEMS wafer (3; 3').

IPC 8 full level

B81C 1/00 (2006.01)

CPC (source: EP US)

B81C 1/00333 (2013.01 - EP US); **B81C 2201/019** (2013.01 - EP US); **B81C 2203/0118** (2013.01 - EP US)

Citation (search report)

See references of WO 2011026699A1

Citation (examination)

EP 1961696 A1 20080827 - KYOCERA CORP [JP]

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)

DE 102009029184 A1 20110310; CN 102482074 A 20120530; EP 2473438 A1 20120711; KR 20120068850 A 20120627; US 2012235252 A1 20120920; WO 2011026699 A1 20110310

DOCDB simple family (application)

DE 102009029184 A 20090903; CN 201080039064 A 20100802; EP 10739911 A 20100802; EP 2010061185 W 20100802; KR 20127005655 A 20100802; US 201013393412 A 20100802